



DA3X108K0L

Silicon epitaxial planar type

For small current rectification
 DA2J108 in Mini3 type package

■ Features

- Small reverse current IR
- High reverse voltage VR
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: 26

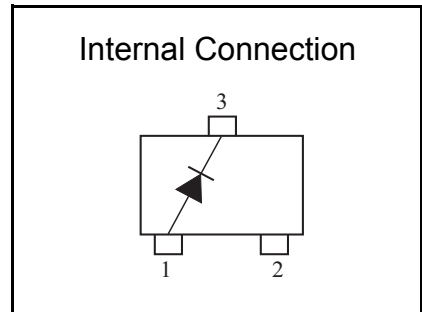
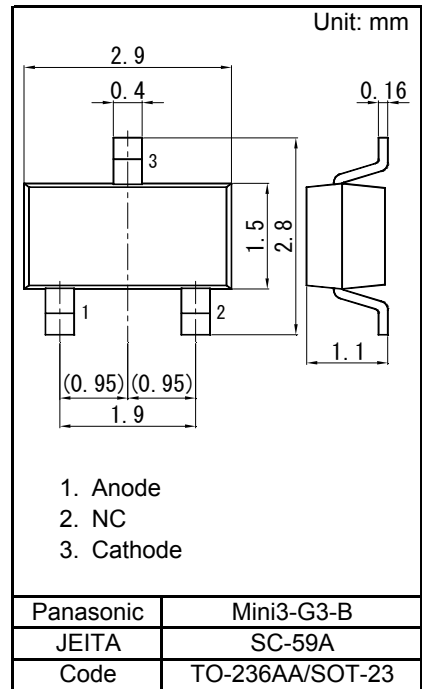
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	300	V
Maximum peak reverse voltage	VRM	300	V
Output current (Average)	IO (AV)	200	mA
Repetitive peak forward current	IFRM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) *1: t = 1 s

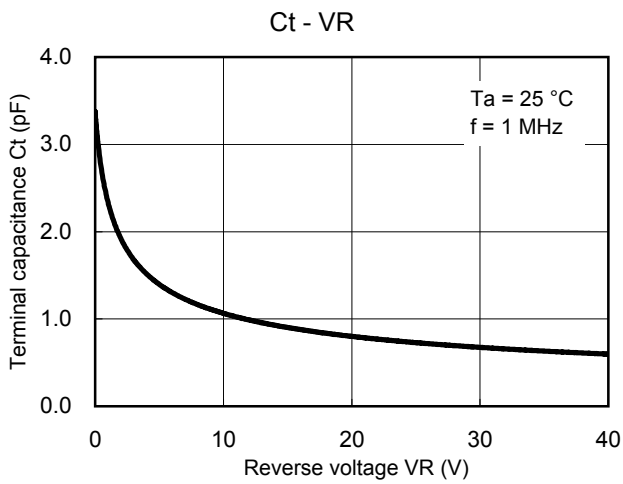
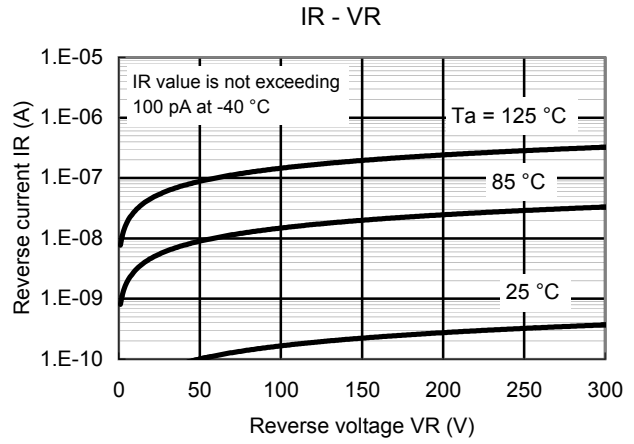
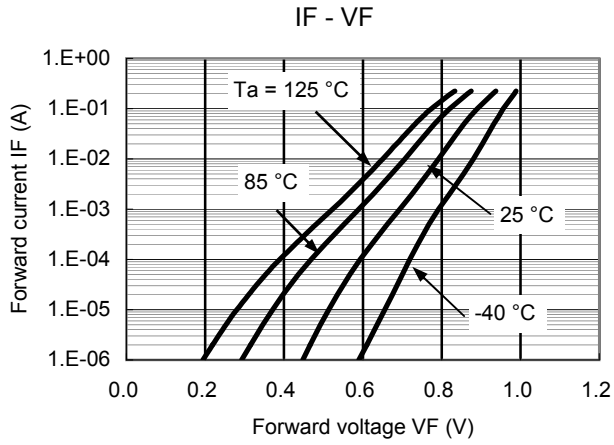


■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA			1.2	V
Reverse current	IR1	VR = 200 V			200	nA
	IR2	VR = 300 V			1	μA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		3.5		pF

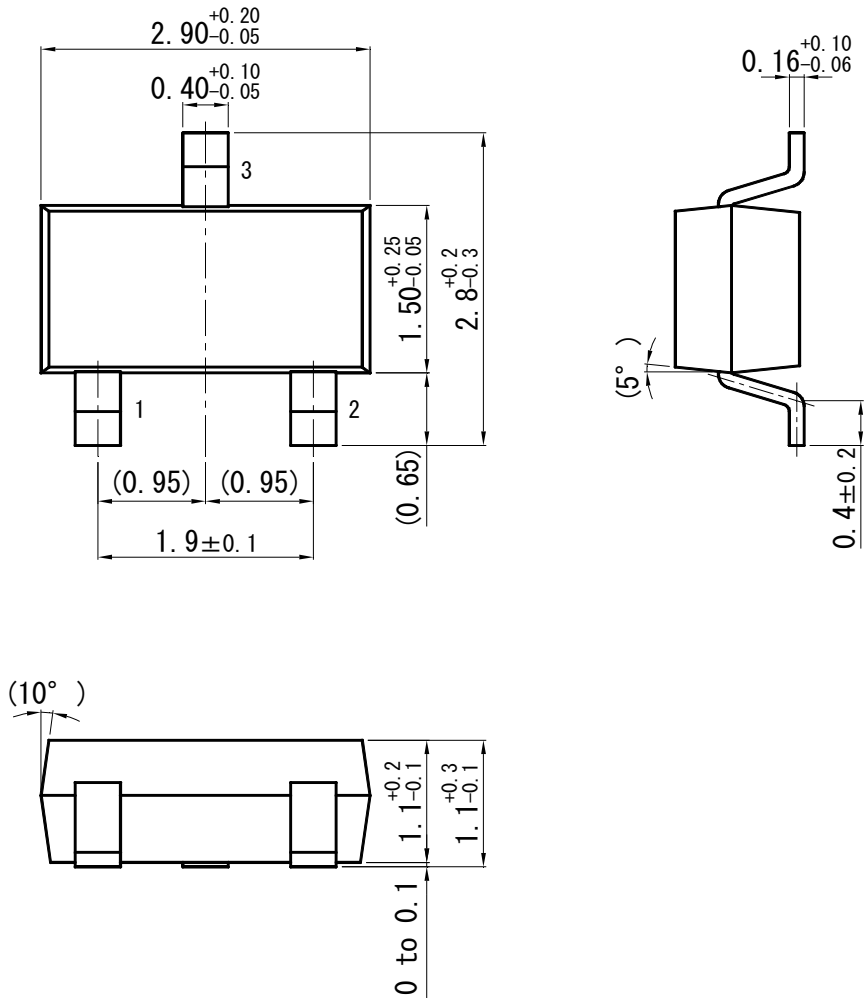
- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 3 MHz.

Technical Data (reference)

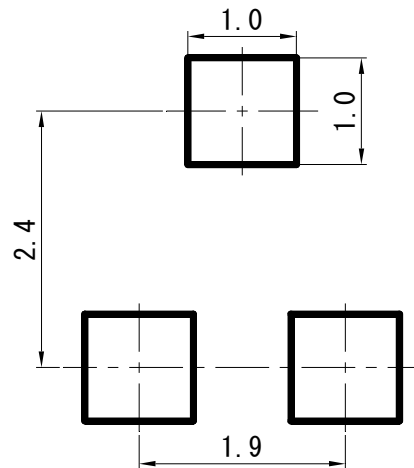


Mini3-G3-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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